

07-05-2000



101396988

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Atty Docket No: HAG 127

In re application of: Nakano et al.  
Serial No: 09/515,134  
Filed: February 29, 2000  
For: Silicon Carbide Film And Method For Manufacturing The Same  
Art Unit:  
Examiner:



I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on June 26, 2000

PATENT ASSIGNMENT COVER SHEET

Assistant Commissioner for Patents  
Washington, D. C. 20231

Cristine M. V. 1000  
June 23, 2000

Sir:

Date 6/26/2000

Please record the attached original document or copy thereof. Total number of pages (with cover sheet): 2

|  |   |
|--|---|
| <p>1. Name of Conveying Party(ies):<br/><u>Yukitaka NAKANO; Hiroyuki NAGASAWA; Kuniaki YAGI; Takamitsu KAWAHARA</u></p> <p>2a. Name and Address of Receiving Party(ies):<br/>Name: <u>Hoya Corporation</u><br/>Address: <u>7-5, Naka-Ochiai 2-chome, Shinjuku-ku, Tokyo Japan</u></p> <p>2b. Name and Address of Receiving Party(ies):<br/>Name: _____<br/>Address: _____</p> <p>3. Nature of Conveyance<br/><input checked="" type="checkbox"/> Assignment<br/><input type="checkbox"/> Merger<br/><input type="checkbox"/> Security Agreement<br/><input type="checkbox"/> Change of Name<br/><input type="checkbox"/> Other _____<br/><input checked="" type="checkbox"/> Execution Date: <u>4/10/2000</u></p> <p>4. Application Number(s) or Patent number(s) (If this document is being filed together with a new application, the execution date of the application is: _____)</p> <p>4a. Patent Application No.(s) <u>09/515,134</u></p> <p>4b. Patent No.(s) _____</p> | <p>5. Name and Address of Party to Whom Correspondence Concerning Document Should be Mailed:<br/><u>Edward D. Manzo, Esq.</u><br/><u>COOK, ALEX, McFARRON, MANZO, CUMMINGS &amp; MEHLER, LTD.</u><br/><u>200 West Adams Street, Suite 2850</u><br/><u>Chicago, Illinois 60606</u></p> <p>6. Total Number of Applications and Patents Involved: <u>1</u></p> <p>7. Total Fee (37 CFR 3.41): <u>\$40.00</u><br/>7a. <input checked="" type="checkbox"/> Enclosed<br/>7b. <input checked="" type="checkbox"/> Authorized to be Charged to Deposit Account For Any Deficiency</p> <p>8. Deposit Account Number: <u>50/1039</u><br/>(A duplicate copy of this page is attached)</p> <p>9. Statement and Signature:<br/><i>To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.</i></p> <p><u>Mark J. Murphy</u><br/>Name of Person Signing<br/>Signature<br/>Reg. No. 34,225<br/>Date: June 23, 2000</p> |
|--|---|

DO NOT USE THIS SPACE

**ASSIGNMENT**

**Identity Of The Patent Application.** I am the inventor (or one joint inventor) of a patent application that I am assigning. The patent application I am assigning is entitled SILICON CARBIDE FILM AND METHOD FOR MANUFACTURING THE SAME which I executed on even date herewith. If the patent application has already been filed, it received serial number \_\_\_\_\_ and bears a filing date of February 29, 2000.

**The Assignee and The Assignment.** I assign my patent rights to Hoya Corporation, a corporation organized according to the laws of JAPAN, having a place of business at 7-5, Naka-Ochiai 2-chome, Shinjuku-ku, Tokyo Japan (hereinafter "the Assignee"). The rights I assign are my entire right, title and interest in the invention or improvements disclosed in the patent application and any and all other applications for United States Letters Patent which I may file, either solely or jointly with others, on the invention or improvements, including all continuations, divisionals, and continuations-in-part, and in any and all United States Letters Patent which may be obtained on any of said applications, and in any reissue or extension thereof. I also assign to the Assignee all priority rights under the International Convention. I agree to execute, at the request of the Assignee, all documents in connection with any application for United States letters patent therefor.

**Payment Received.** I am making this assignment in consideration of One Dollar and other good and valuable consideration. I acknowledge the receipt and sufficiency of the consideration.

**Authorizations.** I request the U.S Commissioner of Patents and Trademarks to issue the Letters Patent to the Assignee. I authorize the attorney(s) of record in the application to insert in this assignment document the date and serial number of the application.

**Further Acts.** I agree, upon the request and at the expense of the Assignee, to execute any divisional, continuation or substitute application for the invention or improvements, and any oath, declaration or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon the application. I agree to perform, upon request, any affirmative acts to obtain said Letters Patent of the United States and to vest in the Assignee all rights therein, so that the Letters Patent will be held and enjoyed by the Assignee, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me if this assignment had not been made.

**Interference** In the event that any application or Letters Patent that I now assign becomes involved in interference, I agree to cooperate to the best of my ability in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof.

Yukitaka Nakano April 10, 2000  
Name: Yukitaka NAKANO Date

Hiroyuki Nagasawa April 10, 2000  
Name: Hiroyuki NAGASAWA Date

Kuniaki Yagi April 10, 2000  
Name: Kuniaki YAGI Date

Takamitsu Kawahara April 10, 2000  
Name: Takamitsu KAWAHARA Date